

IN THE CLAIMS:

1.-9. (Canceled)

10. (currently amended) A method for packing an electronic device comprising ~~steps~~ of:

providing a frame having a package area where said electronic device is disposed therein, a connecting arm and a plurality of frame leads with one end of each of said frame leads cut off from said frame which are connected to the connecting arm;

forming an insulating block with said one end of each of said frame leads and a part of said frame embedded on one side of said package area;

~~interconnecting said frame and said plurality of frame leads with said insulating block;~~
partially cutting said connecting arm to insulate said plurality of frame leads against each other; and

electrically connecting said electronic device to said plurality of frame leads through a plurality of wires to form a semi-product having said electronic device, said frame leads, and said wires;

pre-measuring an electric characteristic of said semi-product before being subject to a plastic molding; and

conducting a plastic molding process to pack said semi-product.

11. (original) The method according to claim 10, wherein said electronic device is a coil.

12. (original) The method according to claim 10, wherein said frame is made of metal.

13. (original) The method according to claim 10, wherein said package area is disposed in the center of said frame and in a shape of a rectangle.

14. (original) The method according to claim 10, wherein said insulating block is formed by a plastic molding process.

15. (canceled)

16. (new) The method according to claim 10, wherein said pre-measuring step further comprises a step of replacing a defective component of said semi-product.

17. (new) The method according to claim 10, wherein said conducting step further comprises a step of cutting off said packed semi-product from said frame to form a product.

18. (new) A method for packing an electronic device comprising steps of:

providing a frame having a package area where said electronic device is disposed therein, a connecting arm connected to said frame, and a plurality of frame leads connected to said connecting arm;

forming an insulating block with said one end of each of said frame leads embedded on one side of said package area;

partially cutting said connecting arm to insulate said plurality of frame leads against each other;

electrically connecting said electronic device to said plurality of frame leads to form a semi-product having said electronic device and said frame leads; and

conducting a plastic molding process to pack said semi-product before being subject to a plastic molding.

19. (new) The method according to claim 18, wherein said electrically connecting step further comprises a step of pre-measuring an electric characteristic among said frame leads and said electronic device before said semi-product being subject to a plastic molding.

20. (new) The method according to claim 19, wherein said pre-measuring step further comprises a step of replacing a defective component of said semi-product.

21. (new) The method according to claim 18, wherein said conducting step further comprises a step of cutting off said packed semi-product from said frame to form a product.

22. (new) The method according to claim 18, wherein said electronic device is a coil.

23. (new) The method according to claim 18, wherein said frame is made of metal.

24. (new) The method according to claim 18, wherein said package area is disposed in the center of said frame and in a shape of a rectangle.

25. (new) The method according to claim 18, wherein said insulating block is formed by a plastic molding process.

26. (new) A method for packing an electronic device comprising steps of:
providing a frame having a package area where said electronic device is disposed therein, a connecting arm, and a plurality of frame leads which are connected to said connecting arm;

forming an insulating block with one end of each of said frame leads embedded on one side of said package area;

partially cutting said connecting arm to insulate said plurality of frame leads against each other ; and

electrically connecting said electronic device to said plurality of frame leads.

27. (new) The method according to claim 26, wherein said electrically connecting step further comprises a step of pre-measuring an electric characteristic among said frame leads and said electronic device before being subject to a plastic molding.

28. (new) The method according to claim 26, wherein said providing step further comprising a step of cutting off one end of each of said frame leads originally connected to said frame.

29. (new) The method according to claim 28, wherein said cutting step further comprises a step of turning said one end of each of said frame leads.

30. (new) The method according to claim 26, wherein said method further comprises a step of conducting a plastic molding process to pack said electronic device and said frame leads.